

(54) **EARPHONE**

(30) **Foreign Application Priority Data**

See application file for complete search history.

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(57) **CLAIM**

The ornamental design for an earphone, as shown and described.

DESCRIPTION

FIG. 1 is a front perspective view of an earphone showing my new design;

FIG. 2 is a rear perspective view thereof;

FIG. 3 is a front elevational view thereof;

FIG. 4 is a rear elevational view thereof;

FIG. 5 is a top plan view thereof;

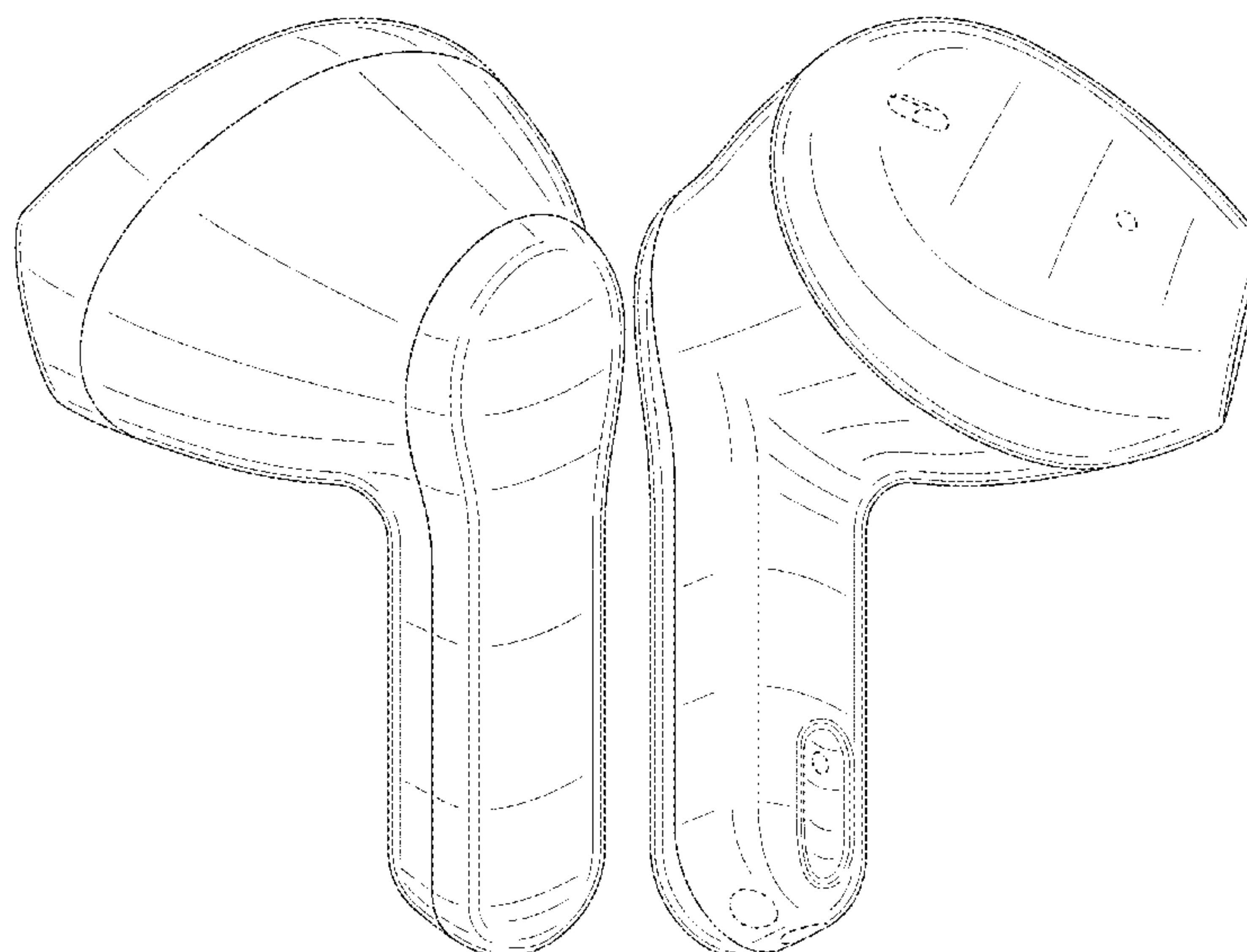
FIG. 6 is a bottom plan view thereof;

FIG. 7 is a right-side elevational view thereof; and,

FIG. 8 is a left-side elevational view thereof.

The broken lines of the drawings represent portions of the earphone that are not part of the claimed design.

1 Claim, 8 Drawing Sheets



(56)

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FIG. 1

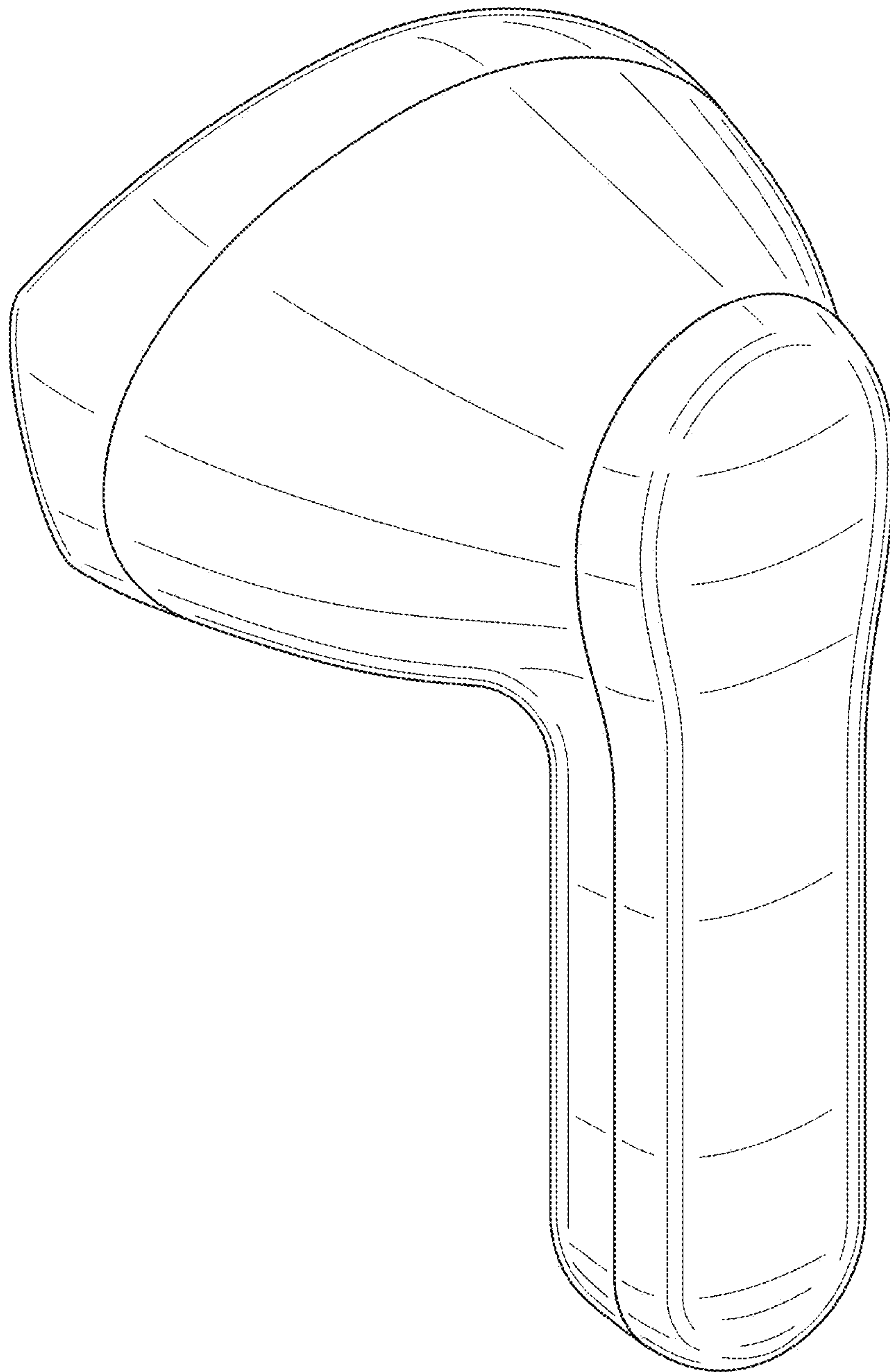


FIG. 2

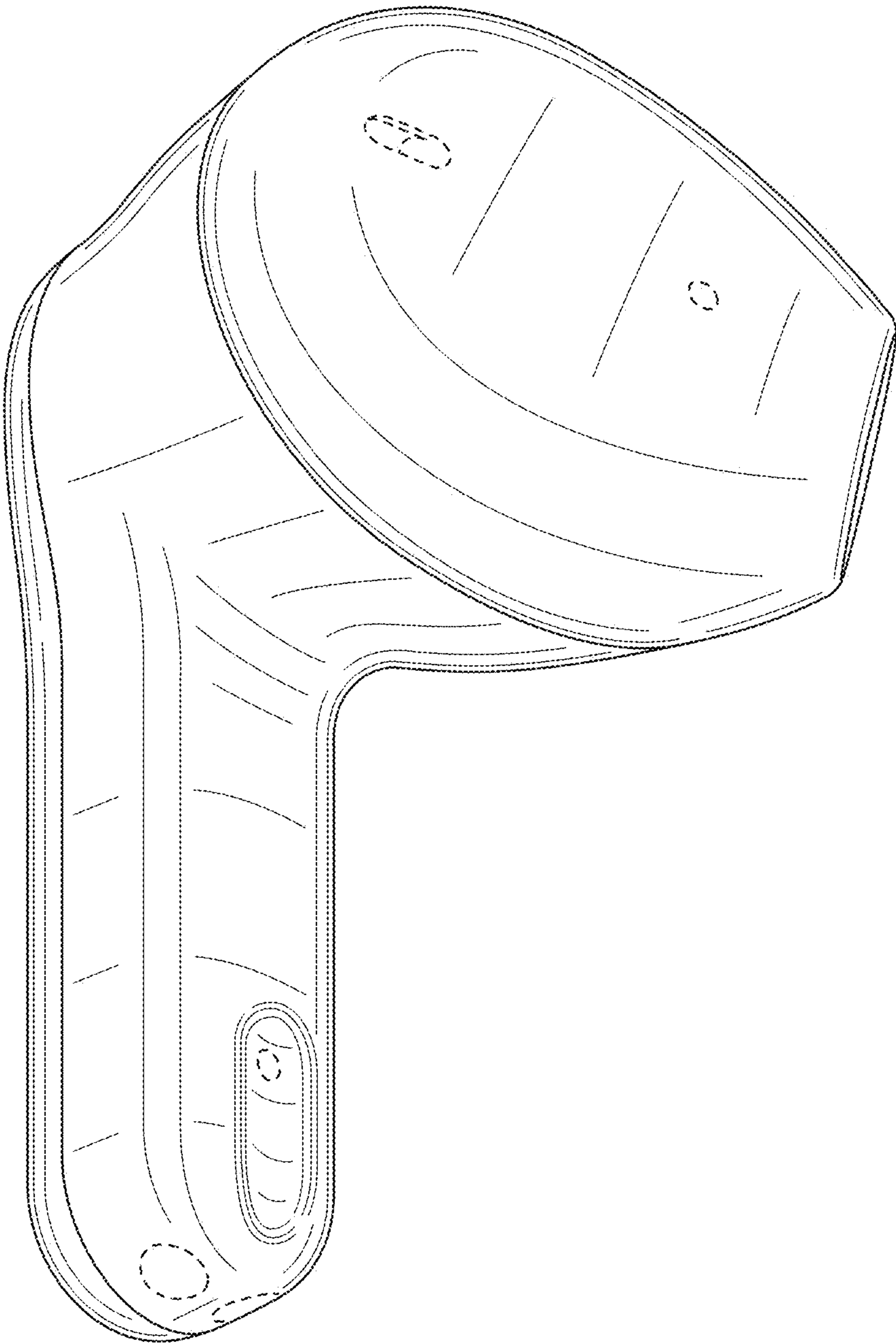


FIG. 3

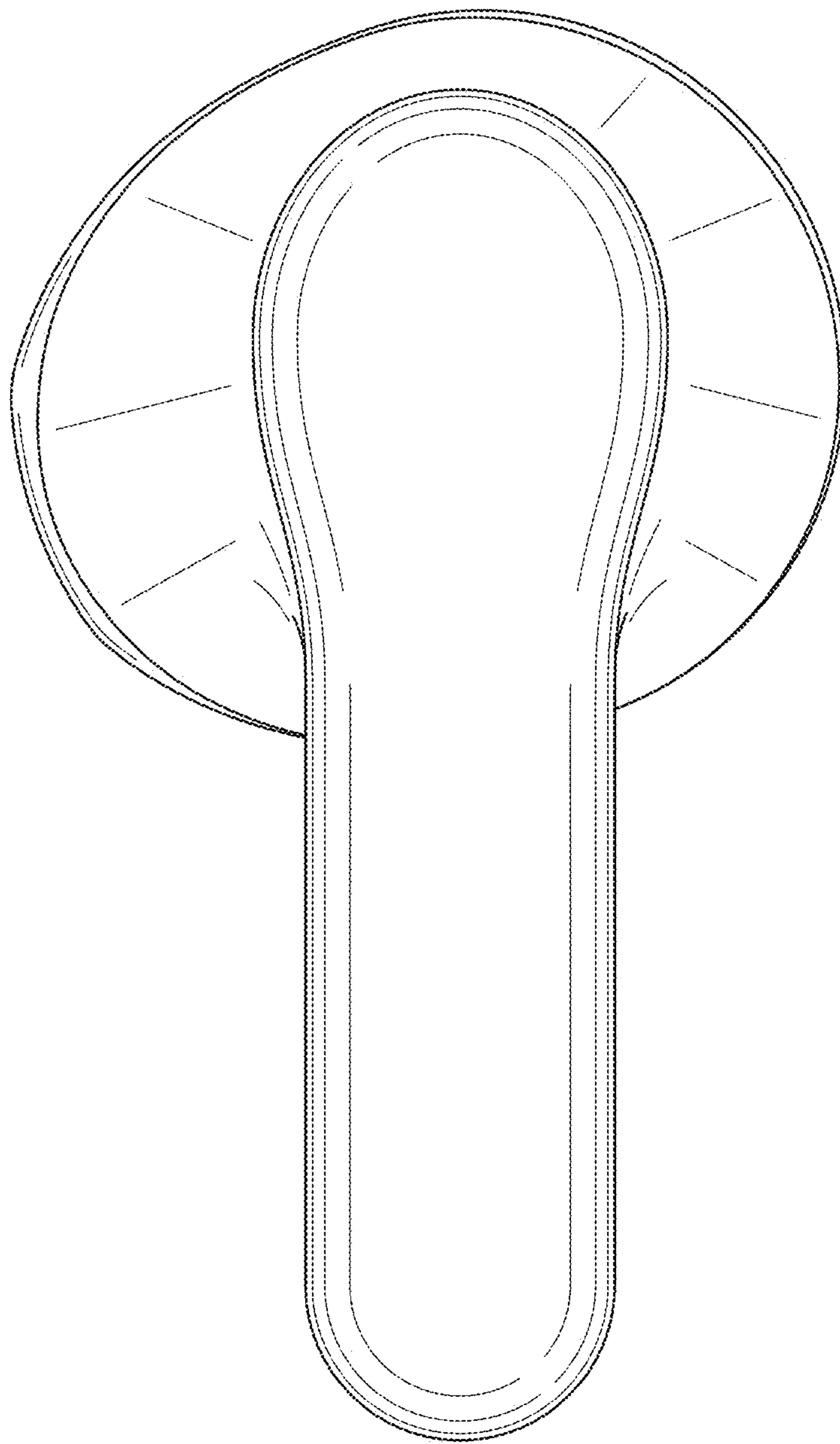


FIG. 4

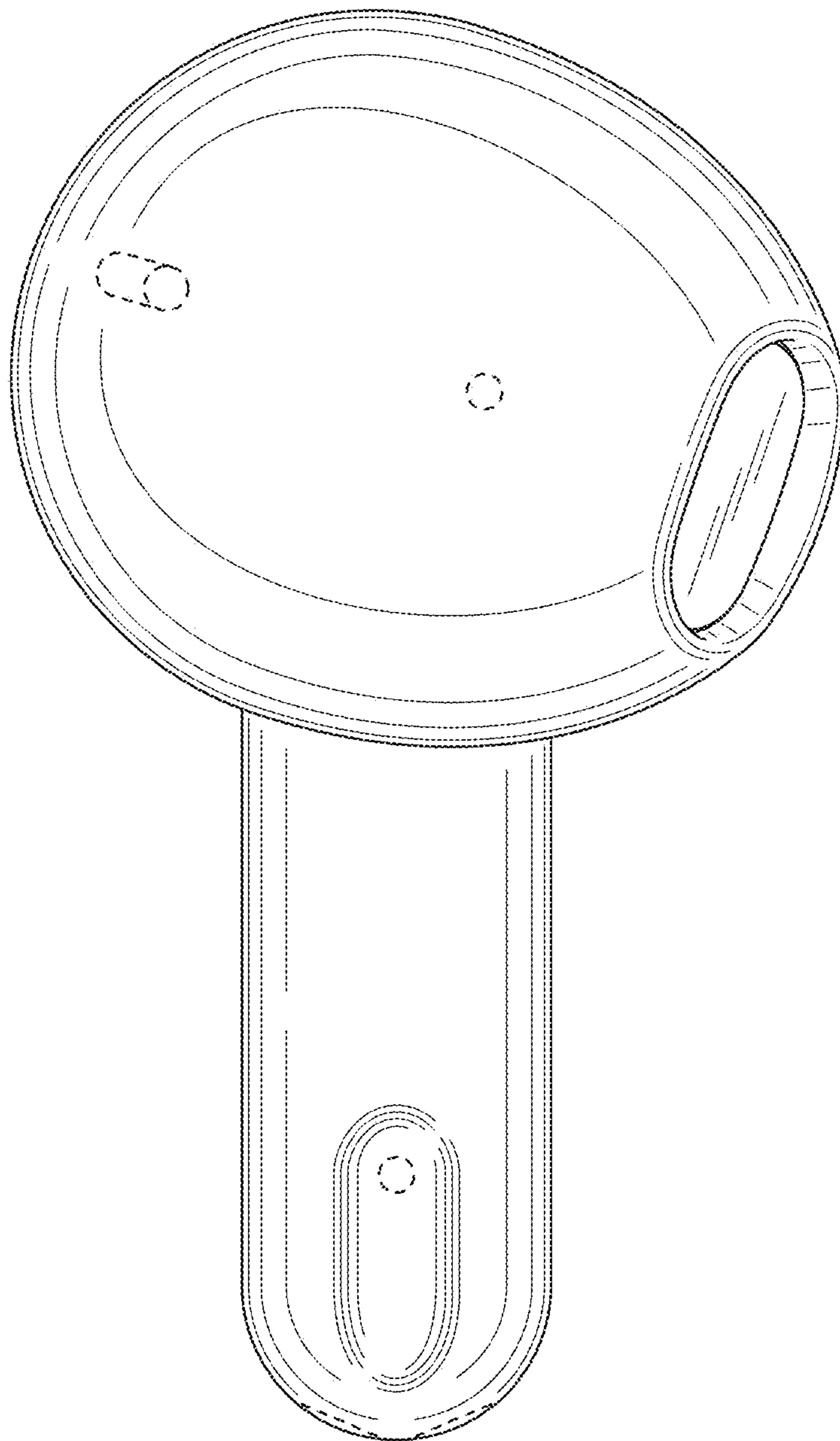


FIG. 5

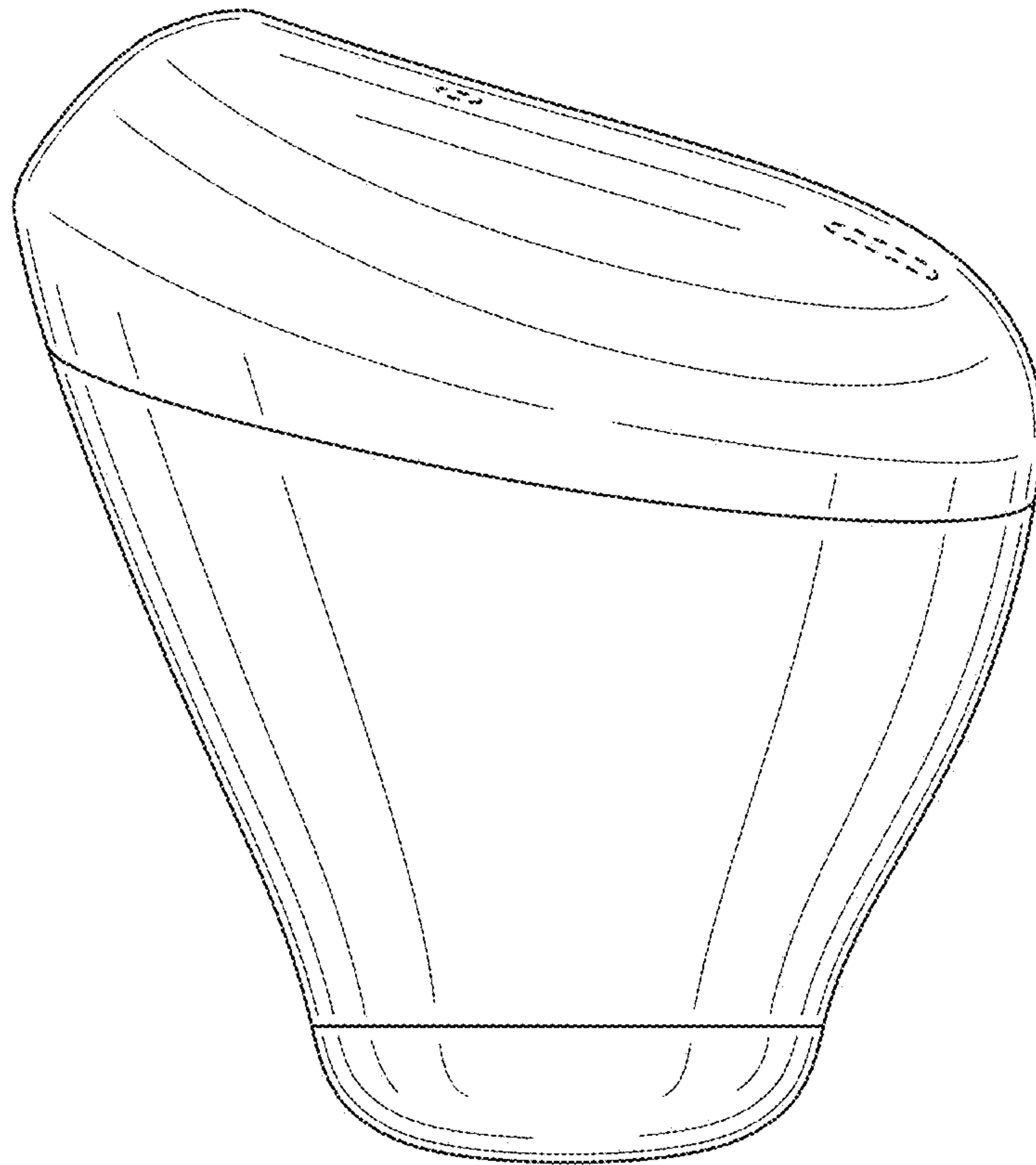


FIG. 6

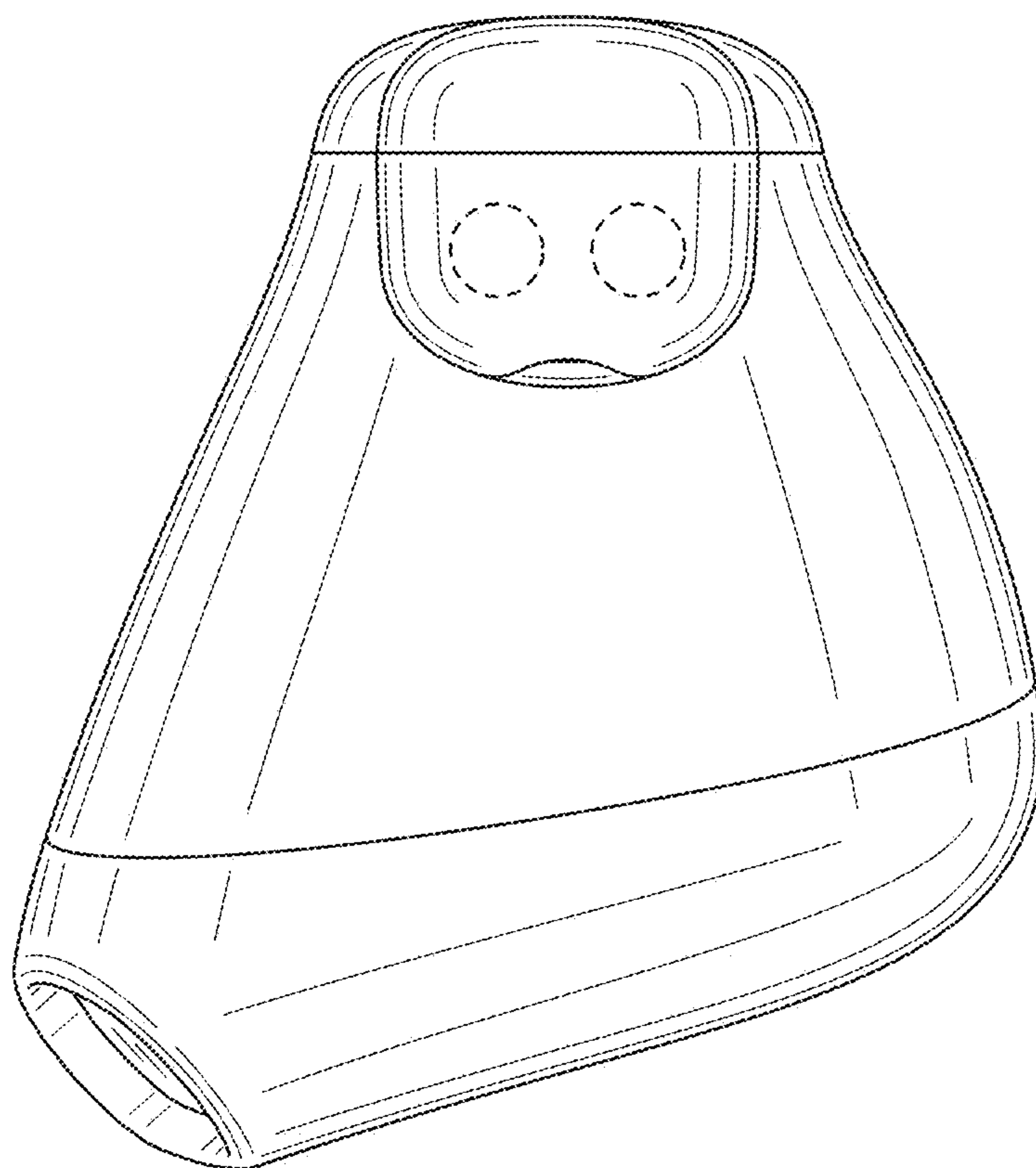


FIG. 7

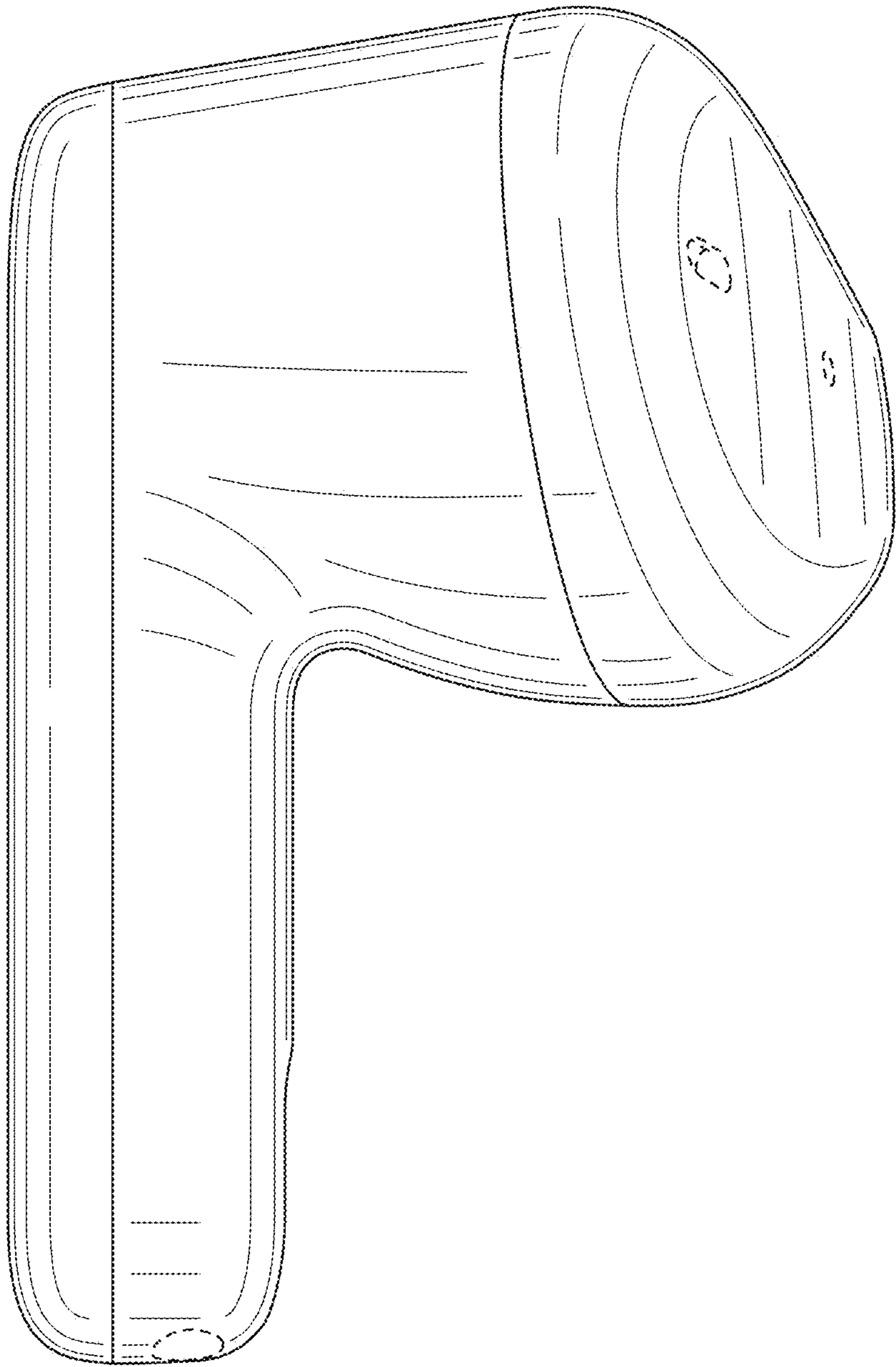


FIG. 8

